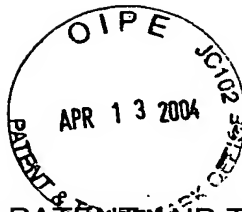


Docket Number: 008312-0290691  
Client Reference: T4SS-01S0768-1



2651  
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re the Application of  
HABATA

Group Art Unit: 2651

Application No.: 10/091,546

Examiner: Unknown

Filed: March 7, 2002

Confirmation No.: 9084

For: METHOD OF MANUFACTURING HEAD SUSPENSION ASSEMBLY AND HEAD  
SUSPENSION ASSEMBLY

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
Mail Stop Patent Application  
P. O. Box 1450  
Alexandria, VA 22313-1450

**RECEIVED**

APR 14 2004

Technology Center 2600

Sir:

Pursuant to 37 CFR 1.56, the attention of the Patent and Trademark Office is hereby directed to the references listed on the attached PTO-1449. Unless otherwise indicated herein, one copy of each foreign reference is attached. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the references be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Applicants respectfully request the Examiner return an initialed copy of the enclosed Form PTO-1449 to Applicants with the next Office communication to indicate that the references have been considered, per MPEP § 609.

This Information Disclosure Statement is being filed more than three months after the U.S. filing date, but before the mailing date of the first Office Action on the merits or the Notice of Allowance.

Pursuant to 37 C.F.R. §1.98(a)(3)(i), the undersigned provides the following statements of relevance for each non-English document listed on the attached PTO-1449.

1. JP 7-287952 describes how to eliminate the need for the backing of a substrate, and to lighten and thin this trace interconnecting body as a whole and reduce load to suspension by forming the trace interconnecting body of an approximately plate-shaped slender conductor, in which rigidity, plastic deformation and thickness are minimized.
2. JP 11-195214 describes how to provide the manufacturing method of a magnetic head device in which the assembly precision of the slider against a suspension and the IC chip for a head are improved and the assembly is easily automated.

3. JP 11-213364 describes how to make easily confirmable the action of a head IC chip and the connection condition by connecting a measurement connection terminal to a first connection terminal, which connects a magnetic head slider, and a second connection terminal, which connects the head IC chip connected to the first connection terminal, and providing the measurement connection terminal at the position other than the first and the second connection terminal positions.
4. JP 2000-311324 describes how to provide a mounting method, wherein while heat is radiated from a reading/writing IC, the reading/writing IC is mounted on an arm portion for supporting a head, and no thermal expansion occurs in the arm itself.
5. JP 2001-52323 describes how to suppress generation of dust from a head IC chip and prevent generation of head crashes by covering the head IC chip with a film.

In addition, the undersigned supplies copies of English abstracts for each of these references. The abstracts provide additional details concerning the relevance of the references to the application. Also, the undersigned supplies a copy of the Japanese Office Action that caused the references to be cited. The Japanese Office Action provides still further details concerning the relevance of the references to the application.

I hereby certify that each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement. 37 CFR 1.97(e)(1).

In addition, I hereby certify that each enclosed document listed on the herewith Form PTO-1449 was first cited in any communication from a foreign patent office in a counterpart foreign counter part application in the attached Japanese Communication (Office Action) issued February 10, 2004, i.e. not more than three months ago. An English language version of the foreign office action and English-language Abstracts are attached for the Examiner's information.

Respectfully submitted,

PILLSBURY WINTHROP LLP



Jeffrey D. Karceski

Reg. No. 35914

Tel. No. (703) 905-2110

Glenn T. Barrett

Reg. No. 38705

Tel. No. (703) 905-2011

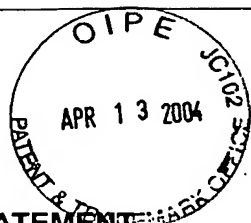
JDK/GTB/smw

Date: April 13, 2004

P.O. Box 10500

McLean, VA 22102

Facsimile: (703) 905-2500



Atty.  
Dkt. No.

M#

Client Ref.

0290691

T4SS-01S0768-1

**INFORMATION DISCLOSURE STATEMENT  
BY APPLICANT**

Applicant: HABATA

Appln. No.: 10/091,546

Filing Date: March 7, 2002

Date: April 13, 2004

Page

1

of

1

Examiner: Unassigned

Group Art Unit: Unassigned

**U.S. PATENT DOCUMENTS**

Examiner's Initials*	Document Number	Date MM/YYYY	Name (Family Name of First Inventor)	Class	Sub Class	Filing Date (if appropriate)
	AR					
	BR					
	CR					
	DR					
	ER					
	FR					
	GR					
	HR					
	IR					
	JR					
	KR					
	LR					
	MR					
	NR					

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**FOREIGN PATENT DOCUMENTS**

	Document Number	Date MM/YYYY	Country	Inventor Name	English Abstract		Translation Readily Available	
					Enclosed	No	Enclose	No
OR	7-287952	10/1995	JAPAN	Jeffrey et al.	x			
PR	11-195214	07/1999	JAPAN	Shiraishi et al.	x			
QR	11-213364	08/1999	JAPAN	Morita et al.	x			
RR	2000-311324	11/2000	JAPAN	Shimizu et al.	x			
SR	2001-52323	02/2001	JAPAN	Kira et al.	x			
TR								
UR								
VR								
WR								
XR								

**OTHER (Including in this order Author, Title, Periodical Name, Date, Pertinent Pages, etc.)**

YR	Japanese Patent Office Action dated February 10, 2004.
ZR	
AAR	
BBR	
CCR	
DDR	

Examiner

Date Considered:

\*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.